METHODS FOR PACKAGING MICROELECTRONIC DEVICES AND
MICROELECTRONIC DEVICES
FORMED USING SUCH METHODS

ABSTRACT OF THE DISCLOSURE

A microelectronic device that includes a microelectronic die (110a, 110b) having an active side (111a, 111b) coupled to a surface of a support member (120). The microelectronic die has a backside (113a, 113b) opposite the active side, a peripheral side (118a, 118b) extending at least part way between the active and the backside, and at least one through-wafer interconnect (114a, 114b) a portion of which (116a, 116b) has been exposed. After mounting the die to the support an encapsulant (130) is applied to the dies so that a portion of the encapsulant is laterally adjacent to the peripheral side of the die. A redistribution structure (142) is applied directly to the backside of the die in electrical contact with the exposed portion of the through-wafer interconnect.

Figure: 7